

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.(original) A method to improve heat dissipation in a magnetic shield, comprising:

providing said shield in the form of a layer of ferromagnetic material on a substrate;

inserting a layer of non-magnetic material, having a thermal conductivity greater than about 300 W/m.K, between said shield and said substrate; and

splitting said shield into two opposing parts separated by a gap.

2. (original) The method described in claim 1 wherein said thermally conductive layer of non-magnetic material is selected from the group consisting of Cu and NiCu.

3. (original) The method described in claim 1 wherein said thermally conductive layer of non-magnetic material is deposited to a thickness between about 1 and 2 microns.

4. (original) The method described in claim 1 wherein said gap separating said opposing shield parts is between about 4 and 10 microns wide.

5-35. Canceled